

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

Production Test Procedure

Receiver Unit 2 Low RCU2L

PCB nr.: 03114

	Organisatie / Organization	Datum / Date
Auteur(s) / Author(s): Henri Meulman	ASTRON	11-03-2022
Controle / Checked: Paulus Kruger	ASTRON	
Goedkeuring / Approval: Nico Ebbendorf	ASTRON	10-03-2022
Autorisatie / Authorisation: Handtekening / Signature Wim van Cappellen	ASTRON	

© ASTRON All rights are reserved. Reproduction in whole or in part is prohibited without written consent of the copyright owner.



This publication is part of the project DURLLO (with project number 175.2017.012 of the research programme "Investerings NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

Distribution list:

Group:	Others:
Henri Meulman Gijs Schoonderbeek Sieds Damstra Nico Ebbendorf Paulus Kruger	

Document history:

Revision	Date	Chapter / Page	Modification / Change
0.1	09-03-2022	-	Draft
0.2	10-03-2022		Update
1.0	11-03-2022		Final



This publication is part of the project DUPLLO (with project number 175.2017.012 of the research programme "Investeren NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

Table of contents:

1	Introduction.....	4
1.1	Document Scope	4
1.2	List of Terms and acronyms	4
1.3	Applicable documents (AD)	5
1.4	Reference documents (RD)	5
1.5	Test results storage	5
2	Test configuration	7
2.1	Identification of the test article	7
2.2	Objectives of the test	7
2.3	Configuration control	7
2.4	Safety	7
2.5	Test responsibilities	7
2.6	Test facility requirements.....	8
3	Test description	8
3.1	PCB Production verification.....	9
3.1.1	In-line assembly inspections.....	9
3.1.2	Feeder Setup Verification	9
3.1.3	Automated Solder Paste Inspection (SPI / API)	9
3.1.4	Automatic Optical Inspection (AOI)	9
3.2	Functional Tests	11
3.2.1	Test equipment and test software	11
3.2.2	Test setup	12
3.2.3	Power supplies impedance and voltages	14
3.2.4	Monitor and Control	14
3.3	Summary	14
4	Anomalies and procedure variations	14
4.1	Deviations from the step-by-step procedure	15
4.2	Software anomalies	15
4.3	Production failure.....	15
5	Annexes.....	15
5.1	Power supply impedances and voltages	15
5.2	Procedure variations sheets	18
5.3	Test result check list	19



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investeren NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

1 Introduction

1.1 Document Scope

This document is intended for PCB assembly, manufacturers and test facilities. It describes the test that have to be performed on the LOFAR2.0 RCU2L during production. The RCU2L is described in RD.1. For each board the test results have to be recorded. **ASTRON is open for adjustment to this test plan. These adjustments however should be discussed and an update of this document will be made.**

In section 2 an overview of the test configuration, all steps that have to be taken prior to testing, is described. Section 3 describes the verification steps during the assembly steps and to the steps which must be performed on the PCBA or module. How to handle anomalies and procedure variation is described in section 4. Annexes to this document can be found in section 5.

1.2 List of Terms and acronyms

ANSI	American National Standards Institute
AD-n	nth document in the list of Applicable Documents
APSCT	Antenna Processing Subrack Clock distribution and Translator
BOM	Bill Of Material
DMM	Digital multi meter
EMC	Electromagnetic compatibility
ESD	Electrostatic discharge
IPC	Association Connecting Electronics Industries
ICT	In Circuit Test
LOFAR	Low Frequency Array
NCR	Non-Compliant Report
PO	Purchase Order
PCB	Printed Circuit Board
PPS	Pulse per second
PV	Procedure Variation
RCU2L	Receiver Unit 2 Low band
RD-n	nth document in the list of Reference Documents
RoHS	Restriction of Hazardous Substances
SW	Software
TBC	To be confirmed
TCC	Test Control Computer
Vpp	Volt peak-to-peak



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

1.3 Applicable documents (AD)

Ref.nr.	Doc. number	Title	Author
AD.1	EN55022-B	EMC standards	
AD.2	IEC 61000 -4-3	Radiated immunity	
AD.3	IEC 61000 -4-6	Conductive immunity	
AD.4	IEC 62305	Protection against lightning	

1.4 Reference documents (RD)

Ref.nr.	Doc. number	Title	Author
RD.1	PMS00048	RCU2L Product Manufacturing Specifications	Damstra

1.5 Test results storage

The results of all inspections, functional and delivery tests should be stored in the ASTRON data-base. This makes it possible to verify that a test was successful.

The OEM can use its own data base for storing a detailed report on the production process. An export with the summary of the production process has to be transferred to the ASTRON data base. This report should include at least:

- The passing of each step from bare board inspection to final delivery check. Each step should including a time stamp.
- The repairs done on the product

The format of this summary should be a PDF file ready to be imported in the ASTRON database.

Figure 1 and Figure 2 are showing an example of the ASTRON database.



This publication is part of the project DUPLLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

I&S Boarden

Search in ALL fields (also those not displayed here):							
Number	Serial nr.	Type-Version	Status	Location	Project	Housing	Production
		UniBoard2					
437	26287-004	UniBoard2-1.3	Tested	Dwingeloo	ARTS	Uni2Box	14-07-2017
436	26287-003	UniBoard2-1.3	Tested	Dwingeloo	ARTS	Uni2Box	14-07-2017
435	26287-002	UniBoard2-1.3	Tested	Dwingeloo	ARTS	Uni2Box	14-07-2017
434	26287-001	UniBoard2-1.3	Tested	Dwingeloo	ARTS	Uni2Box	14-07-2017
433	26287-005	UniBoard2-1.3	Working	Dwingeloo	ARTS	Uni2Box	14-07-2017
8	26054-003	UniBoard2-1.3	Working	Italy	UniBoard2	Uni2Box	15-12-2015
7	26054-004	UniBoard2-1.3	Errors	JIVE	UniBoard2	Uni2Box	15-12-2015
6	26054-005	UniBoard2-1.3	Working	France Bordeaux	UniBoard2	Uni2Box	15-12-2015
5	26054-002	UniBoard2-1.3	Working	Manchester	UniBoard2	Uni2Box	14-12-2015
4	26054-001	UniBoard2-1.3	Working	France Nancay	UniBoard2	Subrack	15-12-2015
3	26054-007	UniBoard2-1.3	Ready for test	Lab Dwingeloo	UniBoard2		15-12-2015
2	26054-006	UniBoard2-1.3	Working	Duitsland	UniBoard2	Uni2Box	15-12-2015
1	26012-001	UniBoard2-1.3	Working	Demo-Board	UniBoard2	Uni2Box	04-05-2015

Figure 1 Overview of the "I&S Boarden" web form.

Board information

Board information		Wijzigen
Board Type	UniBoard2	
Board Version	1.3	
Serial number	26287-001	
Status	Tested	
Location	Dwingeloo	
Firmware	Switch 2.82c, unb2b	
Production date	14-07-2017	
Project	ARTS	
Housing	Uni2Box	
Schematic		
Repairs	Node 0 VCCRGXB SMPS gedraaid op de print.	
Remarks	B.S. OK ready for firmware test.	
Results		
Bestand 1	R_434_1.jpg	Vervang
Bestand 2	R_434_2.png	Vervang
Bestand 3		Nieuw

Figure 2 Example of one board.



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investerings NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

2 Test configuration

2.1 Identification of the test article

The item under test is the RCU2L. For a description refer to RD-1.

2.2 Objectives of the test

The objective of the test is to fully test all solder joints, press-fit connections and mounting of mechanical part on the RCU2L such that the product can be installed on a remote location. All components should be mounted and placed correctly.

2.3 Configuration control

Prior to the test, the test configuration shall be established and recorded

1. Test equipment type, serial number and calibration due date
2. RCU2L test environment SW (scripts) version/date
3. Test equipment settings

All test results tagged with the relevant serial number shall be stored digitally. The test results shall be available for later evaluation when requested by ASTRON. Copies and or prints of this information shall be available for the test result summary.

The content of the test database shall be handed over to ASTRON after delivery of each production batch.

2.4 Safety

The following ESD and personnel safety precautions shall be taken:

- The board is ESD sensitive. ESD precautions must be taken at any time during the assembly and handling of the board or individual components (use a wrist strap connected to a ground terminal).
- An external fan for cooling shall be used, to prevent overheating of the boards. The test engineer shall verify that the fan is running before a test is performed.

2.5 Test responsibilities

It is the responsibility of the test-designer (ASTRON):

- Design a test with covers all aspects
- Design a test which is easy to perform.
- Design a consistent and repeatable test.

It is the responsibility of the test-conductor:

- Executing the test(s) following the test instructions.

The checklist of section 5.3 can be used as a guideline to verify that all verifications are performed.



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

2.6 Test facility requirements

The environmental specifications of the test facility shall be maintained within the values given below:

- Temperature: 18 °C to 25 °C
- Humidity: 50% to 70%
- Cleanliness: "normal" office environment or better
- EMC protected area as described in EN55022-B [AD.1]
- Radiation and conductive immunised area as described in IEC 61000 [AD.2][AD.3]
- Area protected against lightning as described in IEC 62305 [AD.4]
- Antistatic, ESD protected area (EPA)

3 Test description

This section describes the verifications that are required prior, during and after the production of this PCBA. The purpose of the verifications is to confirm good quality of the assembly process and can be divided in events required during the production of the PCBA (section 3.1) and events after completion of the PCB assembly (section 3.2).

A verification event can be one or a combination of the following actions:

Demonstration	Operation of the system, subsystem or a part of the system that relies on observable, functional operation, not requiring use of instrumentation, special test equipment or subsequent analysis.
Test	Operation of the system, subsystem or a part of the system using instrumentation or other special test equipment to collect data for later analysis.
Analysis	Processing of accumulated data obtained from other qualification methods.
Inspection	Visual examination of system components, documentation, certifications, etc.



This publication is part of the project DUPLLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

3.1 PCB Production verification

Incoming PCB's must be visually inspected for anomalies in order to confirm that a PCB is qualified for the following production step. All PCBs have to full fill the IPC-A-610 standard. All PCBs have to pass an electrical test as specified by IPC-9252 to test all interconnections. Use a copy of the test result check list in 5.3 to record the test data and if the test has passed or failed. The results of the following verifications need to be analysed for each individual board in order to confirm that the board is properly assembled and suitable for the function test.

3.1.1 In-line assembly inspections

The goal of In-line assembly tests are:

- Direct feedback during the product assembly process.
- Verify that the right components are placed at the right location.

3.1.2 Feeder Setup Verification

During the filling of the pick and place machine the feeders containing the components will be checked that the correct reel is placed.

3.1.3 Automated Solder Paste Inspection (SPI / API)

Automated solder paste inspection is used to verify that the right amount of solder paste is placed on the board. With the right amount of paste well defined solder joints can be made without spoiling solder (loose solder joints). In Figure 3 an example of SPI is shown.

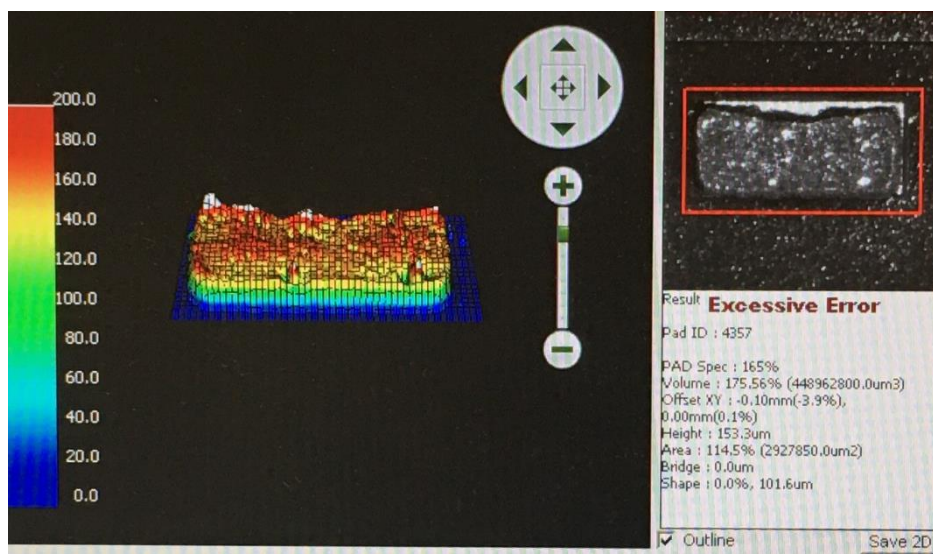


Figure 3 Example of Automated Solder Paste Inspection

3.1.4 Automatic Optical Inspection (AOI)

Automated optical inspection should be used to verify that all parts are placed at the correct location with the correct rotation and the correct alignment. In Figure 4 an image of a single component AOI is shown.



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

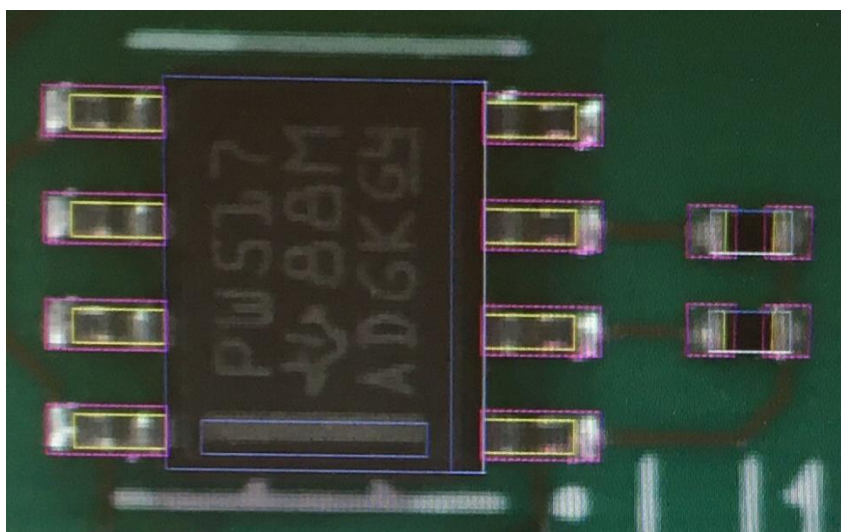


Figure 4 Image of an AOI scan of a SOIC8 package

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

3.2 Functional Tests

The purpose of the functional test as described in this section, is to confirm that the board is properly assembled. These tests can also indicate assembly issues such as short- and open circuits as well as missing or misplaced components.

3.2.1 Test equipment and test software

In Table 1 summarizes the equipment that is required to test RCU2L.

Table 1 List of test equipment

Equipment	Part Number	Serial Number	Calibration due date
Digital Multi Meter			
Test Control Computer			
Power supply 3x			
AP Subrack			
10 MHz clock with pps			
Noise generator			
DC dummy loads			

The RCU2L will be tested in two separate test setup:

1. RCU2L testbench:
In this test the power supplies and the digital part of the board will be tested including the optional programming of the PIC controller.
2. RCU2L Subrack test:
In this test the signal chain, including the analogue (RF) circuits and the ADC, will be tested.

The test software (scripts) will be running in the Test Control Computer (TCC), see Table 2 for an overview of the test software. The TCC combines the functions of the specific RCU2L test. It will be used to set the required test configuration for a certain function or measurement. Functions can be commanded, the corresponding monitoring values and housekeeping parameters of the RCU2L will be monitored and evaluated for correctness by the test control computer. The computer will show a pass/fail on each of the functional test parameters and store the test results in the database.

Table 2 List of software package on the Test control computer.

Software package	Version	Location
Python		
RCU2L_testbench.py		
RCU2L_production.py		



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

3.2.2 Test setup

In Figure 5 the testbench test setup for the RCU2L is shown.

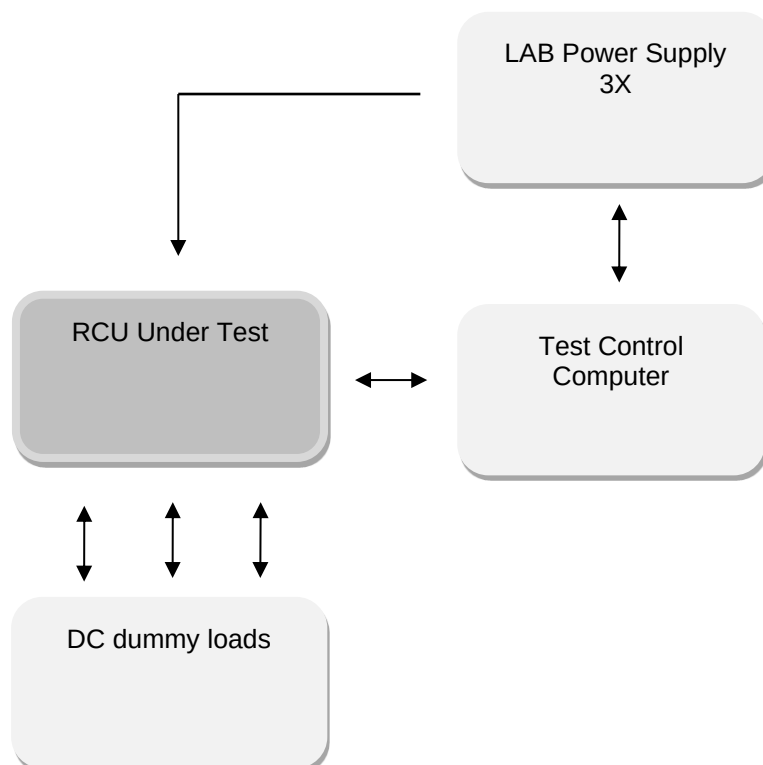


Figure 5 RCU2L production test setup.

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

In Figure 66 the test setup for the RCU2L is shown.

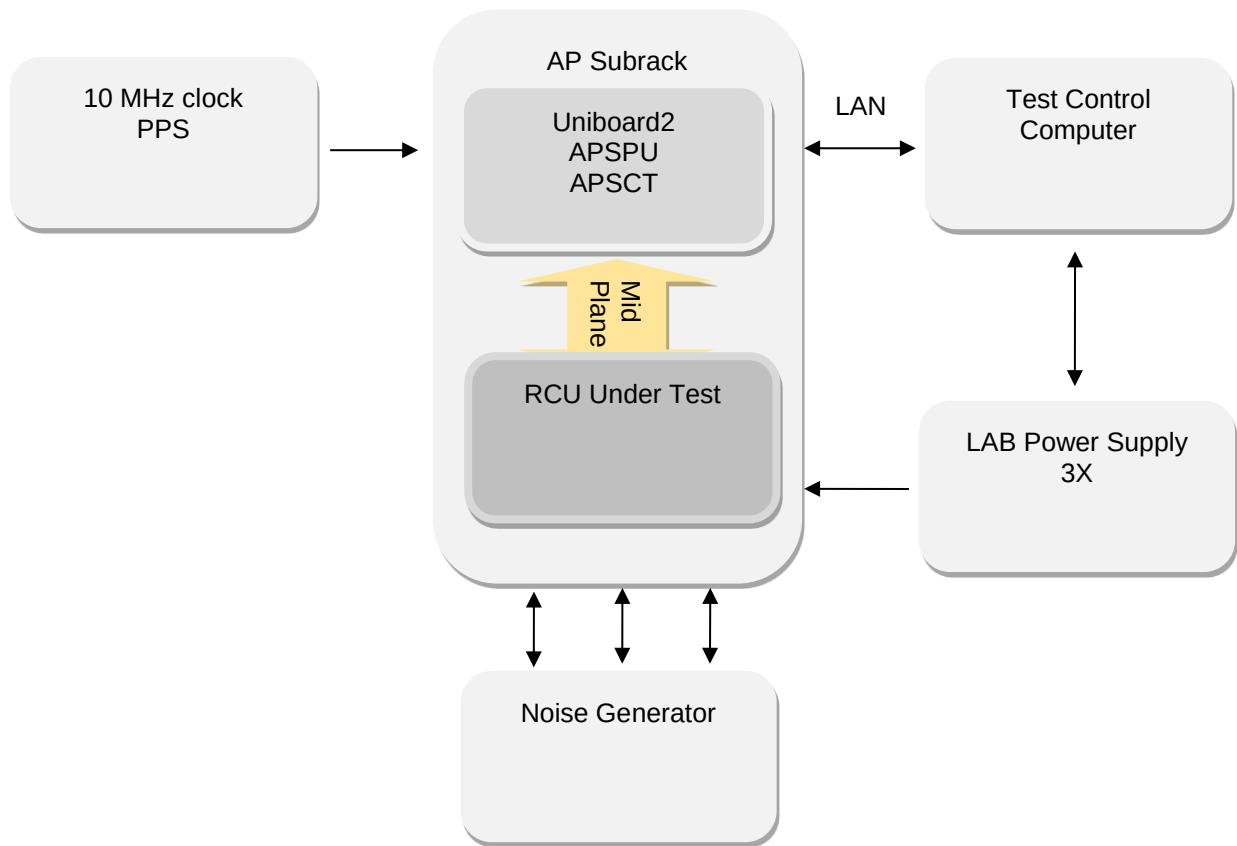


Figure 6 RCU2L production test setup.

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

Before the functional test can be performed the following steps have to be done:

1. Start computer
2. Start command window to run python script
3. Start web browser to store test results.
4. Connect RCU2L inside the AP Subrack
5. Prepare power supply power off
6. Connect the Noise generator and DC dummy loads to the F-connector

3.2.3 Power supplies impedance and voltages

The power supplies are measured during the functional test. In case a module does not start-up correctly the local power supplies have to be measured as described in 5.1.

3.2.4 Monitor and Control

The monitor and control interface, including programming of the EEPROM, is tested by running the python script: RCU2L_Production.py. This should be done by performing the following steps:

1. Connect the Noise generator and DC dummy loads to the F-connector
2. Run RCU2L_production.py
3. Check if run was successfully
4. Upload results.txt into the database.

3.3 Summary

In **Error! Reference source not found.** an overview steps during the functional test and the test times are shown.

Table 3 Estimated test time.

Item	Est. test time	Functional test
Install in test system	20 s	
Run python script	3 min	Monitor and Control
Install in Subrack test setup	20 s	
Run python script	2 min	Analog (RF) test
Store results	1 min	
Sum	6 min 40 s	

4 Anomalies and procedure variations

During a test, several types of anomalies or deviations may occur. Depending on the type, the anomaly or deviation has to be documented. In the following subsection actions which have to be taken on the possible anomalies and deviations are described.



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

4.1 Deviations from the step-by-step procedure

A Procedure Variation (PV) have to be added to the Procedure Variation Sheet in section. The PV shall have a unique number and explain which test step(s) have changed and for what reason. The PV reference must be added at the relevant test step. The PV must be communicated with the customer ASTRON and eventually agreed before proceeding with the tests depending on the impact on the test.

4.2 Software anomalies

Small mistakes in the test software which do not have impact on the overall flow of the test and need not to be discussed with the customer. Persistence malfunction of the software must be communicated with the customer ASTRON such that actions can be taken. Contact information can be found in the PMS [RD.1]

4.3 Production failure

When a test step fails (i.e. the pass/fail criteria = fail) during the test and the failure cannot be corrected by a small change to the test software (see 4.2 above), the following options are possible:

- Failure diagnosis to be performed to pin-point the problem to a replaceable item. The correction on the PCBA has to be stored in the component database.
- When the failure is such that testing has to be stopped and immediate action has to be taken: Inform the customer ASTRON and together will be decided if testing can continue and whether Software Problem Report (SPR) or PV must be raised. Any PV/SPR reference must be added at the relevant test step.

5 Annexes

5.1 Power supply impedances and voltages

In case a DC power supply module does not power up correctly, the impedance of the power supplies have to be measured, using an Ohm meter to determine that here is no short circuit at the power connection. In



This publication is part of the project DURLLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

Table 4 the minimal impedance's are shown. In brackets, the typical value is shown. These impedance's are measured to ground unless otherwise noted. After the impedances are successfully measured the power supply can be connected and switched on. On the board the local DC powers are made. With the multi meter the voltages have to be measured as well. In the locations and boundaries of the voltages are shown.



This publication is part of the project DUPLLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

Table 4 Power supply impedances and voltages.

Power supply	Location	Impedance	Voltage	Automated Monitoring	Schematic node
VIN_ANA_P	F1	tbd	$\geq 7.6\text{ V}$	no	VCC_ANALOG_IN
VIN_DIG_P	F2	tbd	$\geq 2.7\text{ V}$	no	VDD_DIG_IN
RCU_PWR_1V8	C197 pin 1	tbd	$> 1.71\text{ V}$	RCU_PWR_1V8_R	VDD_1V8_ADCS
RCU_PWR_2V5	C260 pin 1	tbd	$> 2.38\text{ V}$	RCU_PWR_2V5_R	VDD_2V5_CLK
RCU_PWR_3V3	C199 pin 1	tbd	$> 3.14\text{ V}$	RCU_PWR_3V3_R	VDD_3V3
RCU_PWR_ANT_VIN_0	R4_A0 pin 1	tbd	$> 7.6\text{ V}$	RCU_PWR_ANT_VIN_R	VIN_LBA
RCU_PWR_ANT_VIN_1	R4_A1 pin 1	tbd	$> 7.6\text{ V}$	RCU_PWR_ANT_VIN_R	VIN_LBA
RCU_PWR_ANT_VIN_2	R4_A2 pin 1	tbd	$> 7.6\text{ V}$	RCU_PWR_ANT_VIN_R	VIN_LBA
RCU_PWR_ANT_VOUT_0	L57_R0 pin 1	tbd	$> 7.6\text{ V}$	RCU_PWR_ANT_IOUT_R	ANT_P_CH0
RCU_PWR_ANT_VOUT_1	L56_R0 pin 1	tbd	$> 7.6\text{ V}$	RCU_PWR_ANT_IOUT_R	ANT_P_CH1
RCU_PWR_ANT_VOUT_2	L55_R0 pin 1	tbd	$> 7.6\text{ V}$	RCU_PWR_ANT_IOUT_R	ANT_P_CH2
5V Analog Power Channel 0	C188 pin 1	tbd	$> 4.75\text{ V}$	no	VCC_ADC_BUF_CLEAN Buffer Amplifier and ADC Channel 0
5V Analog Power Channel 1	C192 pin 1	tbd	$> 4.75\text{ V}$	no	VCC_ADC_BUF_CLEAN Buffer Amplifier and ADC Channel 1
5V Analog Power Channel 2	C203 pin 1	tbd	$> 4.75\text{ V}$	no	VCC_ADC_BUF_CLEAN Buffer Amplifier and ADC Channel 2
1.8V ADC Channel 0	C190 pin 1	tbd	$> 1.71\text{ V}$	no	AVDD_CLEAN Buffer Amplifier and ADC Channel 0
1.8V ADC Channel 1	C194 pin 1	tbd	$> 1.71\text{ V}$	no	AVDD_CLEAN Buffer Amplifier and ADC Channel 0
1.8V ADC Channel 2	C205 pin 1	tbd	$> 1.71\text{ V}$	no	AVDD_CLEAN Buffer Amplifier and ADC Channel 0

After Power On LED D3 should be on. (Power good). This means the “VDD_1V8_ADCS”, “VDD_2V5_CLK” and “VDD_3V3” supply voltages are OK.



This publication is part of the project DUPLO (with project number 175.2017.012 of the research programme "Investeren in NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

Author: H. Meulman	Date of issue: 11-03-2022 Kind of issue: limited	Doc.id : TRP-00023	
	Status: Final Revision: 1.0	File name:TPR00023_RCU2L.docx	

5.2 Procedure variations sheets

(to be copied as necessary)

PROCEDURE VARIATION/ ADDITIONAL ACTIVITIES					
Number	Date/ time	Procedure step/ Test phase	Variation description	Test Dir.	PA



This publication is part of the project DUPLLO (with project number 175.2017.012 of the research programme "Investerings NWO-groot" which is (partly) financed by the Dutch Research Council (NWO).

Doc.nr.: TPR00023
Rev: 1.0
Date: 11-03-2022
Class.:

5.3 Test result check list

Step	Operation	Pass/Fail criterion	Observation	P/F
1.	Equipment calibration	Is the all necessary equipment calibrated?	yes / no	
2.	Record Serial number	Is a label with the ASTRON serial number (Sn: RCU2L-1- . . .) placed?	yes / no	
3.	PCB checked	Are electrical test done? Is the PCB according IPC-A-600	yes / no yes / no	
4.	Paste Inspection completed successful	Was the Paste Inspection completed successful?	yes / no	
5.	Optical Inspection completed successful	Was the Optical Inspection completed successful?	yes / no	
6.	Visual check of assembled board	Are all components correctly placed?	yes / no	
8.	Instruments setup	Test Computer running with correct settings? Power supply at 8V / 1A And connected to Test PC	yes / no	
10.	Python scripts	Was the result of running python script RCU2L_production.py successful? Is LED on front panel Green?	yes / no yes / no	
11.	Disconnect RCU2L for test-setup	Is RCU2L, without damages, disconnected from the test jig?	yes / no	
12.	Store test results	Are the RCU2L test results stored in the database?	yes / no	